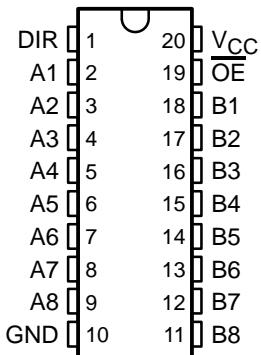
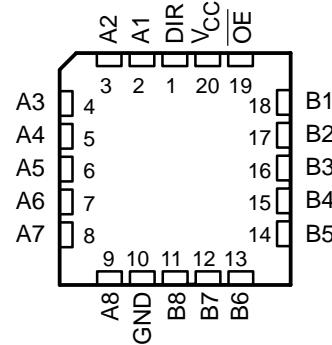


- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80- μ A Max I_{CC}
- Typical $t_{pd} = 12$ ns
- ± 6 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max
- True Logic

SN54HC645 ... J OR W PACKAGE
SN74HC645 ... DW, N, OR NS PACKAGE
(TOP VIEW)



SN54HC645 ... FK PACKAGE
(TOP VIEW)



description/ordering information

These octal bus transceivers are designed for asynchronous two-way communication between data buses. These devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending upon the level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the device so the buses are effectively isolated.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube	SN74HC645N	SN74HC645N
	SOIC – DW	Tube	SN74HC645DW	HC645
	SOP – NS	Tape and reel	SN74HC645DWR	
-55°C to 125°C	SOP – NS	Tape and reel	SN74HC645NSR	HC645
	CDIP – J	Tube	SNJ54HC645J	SNJ54HC645J
	CFP – W	Tube	SNJ54HC645W	SNJ54HC645W
	LCCC – FK	Tube	SNJ54HC645FK	SNJ54HC645FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS		OPERATION
OE	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



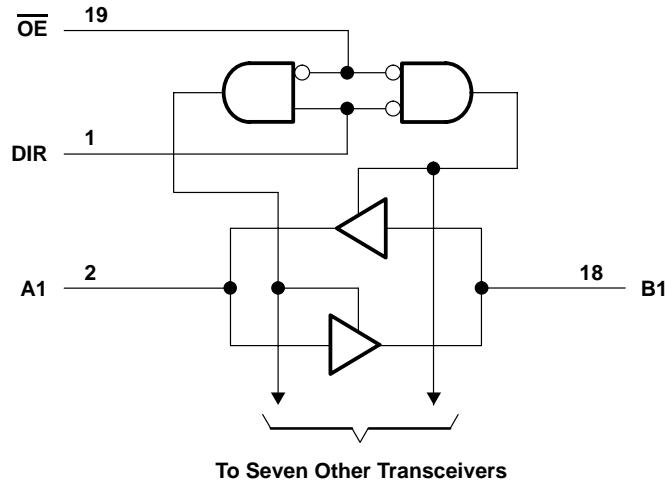
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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54HC645, SN74HC645 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCLS304B – JANUARY 1996 – REVISED DECEMBER 2002

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN54HC645			SN74HC645			UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX		
V _{CC} Supply voltage			2	5	6	2	5	6	V	
V _{IH} High-level input voltage	V _{CC} = 2 V		1.5			1.5			V	
	V _{CC} = 4.5 V		3.15			3.15				
	V _{CC} = 6 V		4.2			4.2				
V _{IL} Low-level input voltage	V _{CC} = 2 V		0.5			0.5			V	
	V _{CC} = 4.5 V		1.35			1.35				
	V _{CC} = 6 V		1.8			1.8				
V _I	Input voltage		0	V _{CC}	0	V _{CC}	0	V _{CC}	V	
V _O	Output voltage		0	V _{CC}	0	V _{CC}	0	V _{CC}	V	
Δt/Δv	Input transition rise/fall time		V _{CC} = 2 V			1000			ns	
			V _{CC} = 4.5 V			500				
			V _{CC} = 6 V			400				
T _A	Operating free-air temperature			-55	125	-40	85	°C		

**SN54HC645, SN74HC645
OCTAL BUS TRANSCEIVERS
WITH 3-STATE OUTPUTS**

SCLS304B – JANUARY 1996 – REVISED DECEMBER 2002

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	$T_A = 25^\circ C$			SN54HC645	SN74HC645	UNIT
			MIN	TYP	MAX	MIN	MAX	
V_{OH}	$V_I = V_{IH}$ or V_{IL}	$I_{OH} = -20 \mu A$	2 V	1.9	1.998	1.9	1.9	V
			4.5 V	4.4	4.499	4.4	4.4	
			6 V	5.9	5.999	5.9	5.9	
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3	3.7	3.84	V
		$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8	5.2	5.34	
		2 V	0.002	0.1	0.1	0.1		
V_{OL}	$V_I = V_{IH}$ or V_{IL}	$I_{OL} = 20 \mu A$	4.5 V	0.001	0.1	0.1	0.1	V
			6 V	0.001	0.1	0.1	0.1	
			$I_{OL} = 6 \text{ mA}$	4.5 V	0.17	0.26	0.4	0.33
		$I_{OL} = 7.8 \text{ mA}$	6 V	0.15	0.26	0.4	0.33	
I_I	DIR or \overline{OE}	$V_I = V_{CC}$ or 0	6 V	± 0.1	± 100	± 1000	± 1000	nA
I_{OZ}	A or B	$V_O = V_{CC}$ or 0	6 V	± 0.01	± 0.5	± 10	± 5	μA
I_{CC}		$V_I = V_{CC}$ or 0, $I_O = 0$	6 V		8	160	80	μA
C_i	DIR or \overline{OE}		2 V to 6 V	3	10	10	10	pF

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ C$			SN54HC645	SN74HC645	UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A or B	B or A	2 V	40	105		160	130	ns
			4.5 V	15	21		32	26	
			6 V	12	18		27	22	
t_{en}	\overline{OE}	A or B	2 V	125	230		340	290	ns
			4.5 V	23	46		68	58	
			6 V	20	39		58	49	
t_{dis}	\overline{OE}	A or B	2 V	74	200		300	250	ns
			4.5 V	25	40		60	50	
			6 V	21	34		51	43	
t_t		A or B	2 V	20	60		90	75	ns
			4.5 V	8	12		18	15	
			6 V	6	10		15	13	

**SN54HC645, SN74HC645
OCTAL BUS TRANSCEIVERS
WITH 3-STATE OUTPUTS**

SCLS304B – JANUARY 1996 – REVISED DECEMBER 2002

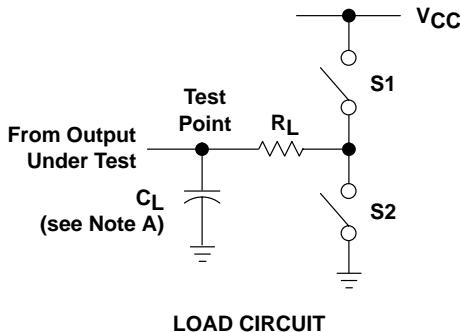
switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC645	SN74HC645	UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A or B	B or A	2 V	54	135	200	170	170	ns
			4.5 V	18	27	40	34	34	
			6 V	15	23	34	29	29	
t_{en}	\overline{OE}	A or B	2 V	150	270	405	335	335	ns
			4.5 V	31	54	81	67	67	
			6 V	25	46	69	56	56	
t_t		A or B	2 V	45	210	315	265	265	ns
			4.5 V	17	42	63	53	53	
			6 V	13	36	53	45	45	

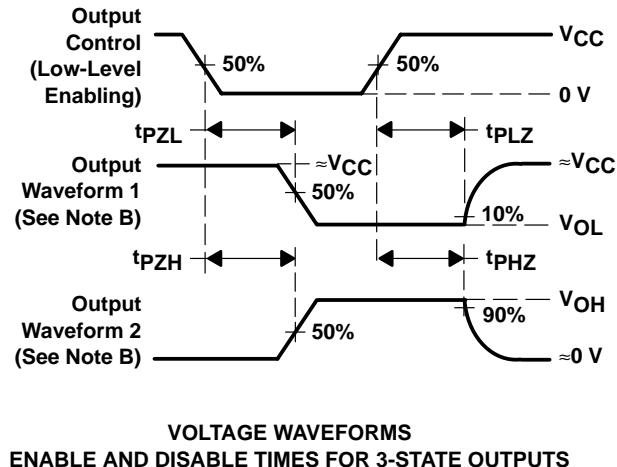
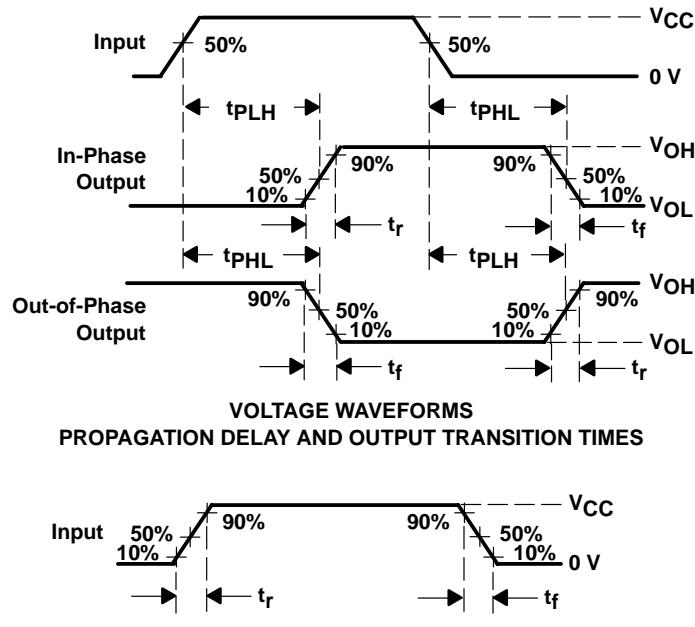
operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance per transceiver	No load	40	pF

PARAMETER MEASUREMENT INFORMATION



PARAMETER	R_L	C_L	S1	S2
t_{en}	1 k Ω	50 pF or 150 pF	Open	Closed
			Closed	Open
t_{dis}	1 k Ω	50 pF	Open	Closed
			Closed	Open
t_{pd} or t_t	—	50 pF or 150 pF	Open	Open



NOTES:

- C_L includes probe and test-fixture capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
- The outputs are measured one at a time with one input transition per measurement.
- t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- t_{PLZ} and t_{PZH} are the same as t_{en} .
- t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN54HC645J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54HC645J	Samples
SN74HC645DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC645	Samples
SN74HC645DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC645	Samples
SN74HC645N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC645N	Samples
SNJ54HC645FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54HC645FK	Samples
SNJ54HC645J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54HC645J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54HC645, SN74HC645 :

- Catalog: [SN74HC645](#)
- Military: [SN54HC645](#)

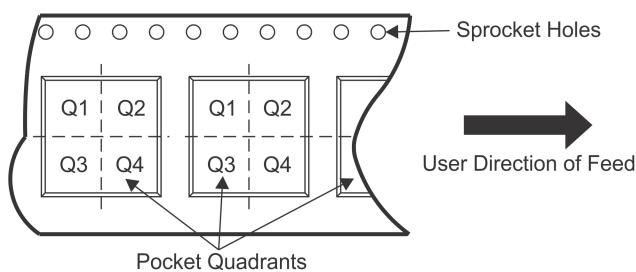
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

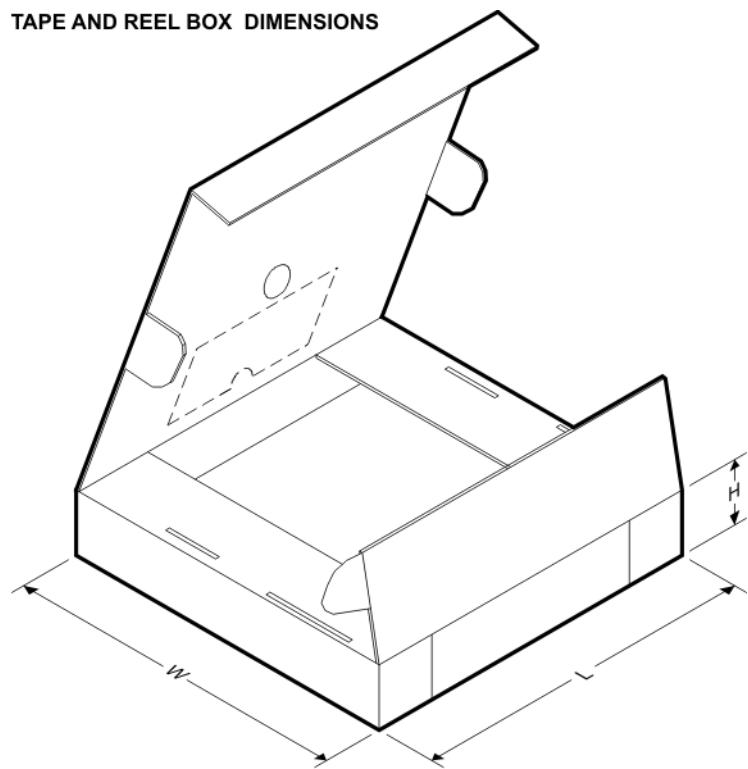
TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


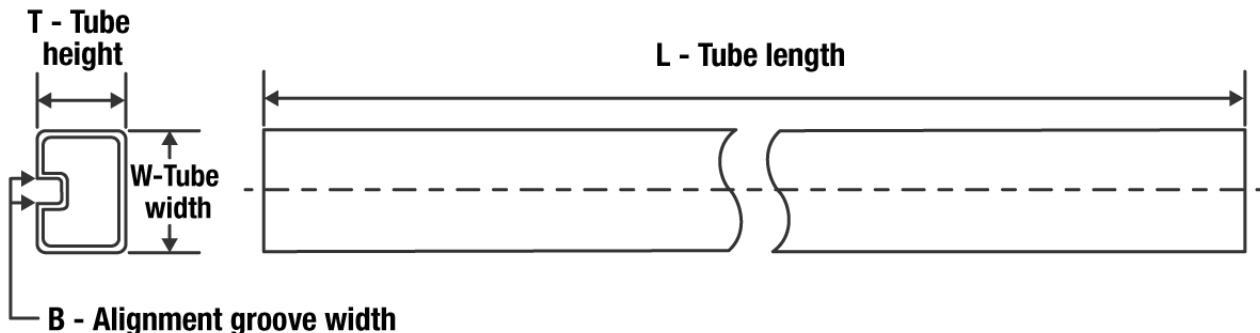
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC645DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC645DWR	SOIC	DW	20	2000	367.0	367.0	45.0

TUBE


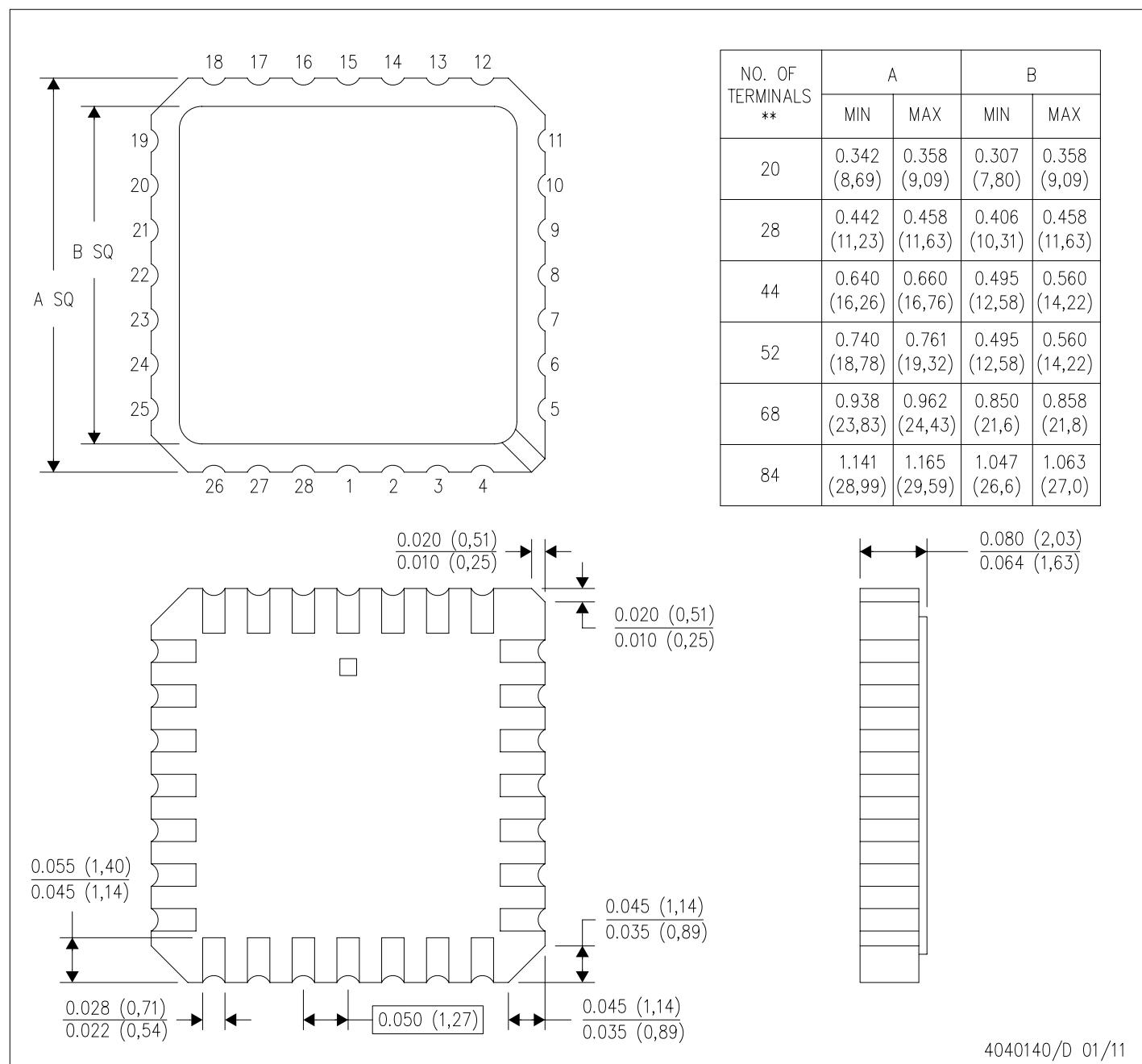
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μ m)	B (mm)
SN74HC645DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74HC645N	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54HC645FK	FK	LCCC	20	1	506.98	12.06	2030	NA

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004

4040140/D 01/11

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

△ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

△ The 20 pin end lead shoulder width is a vendor option, either half or full width.

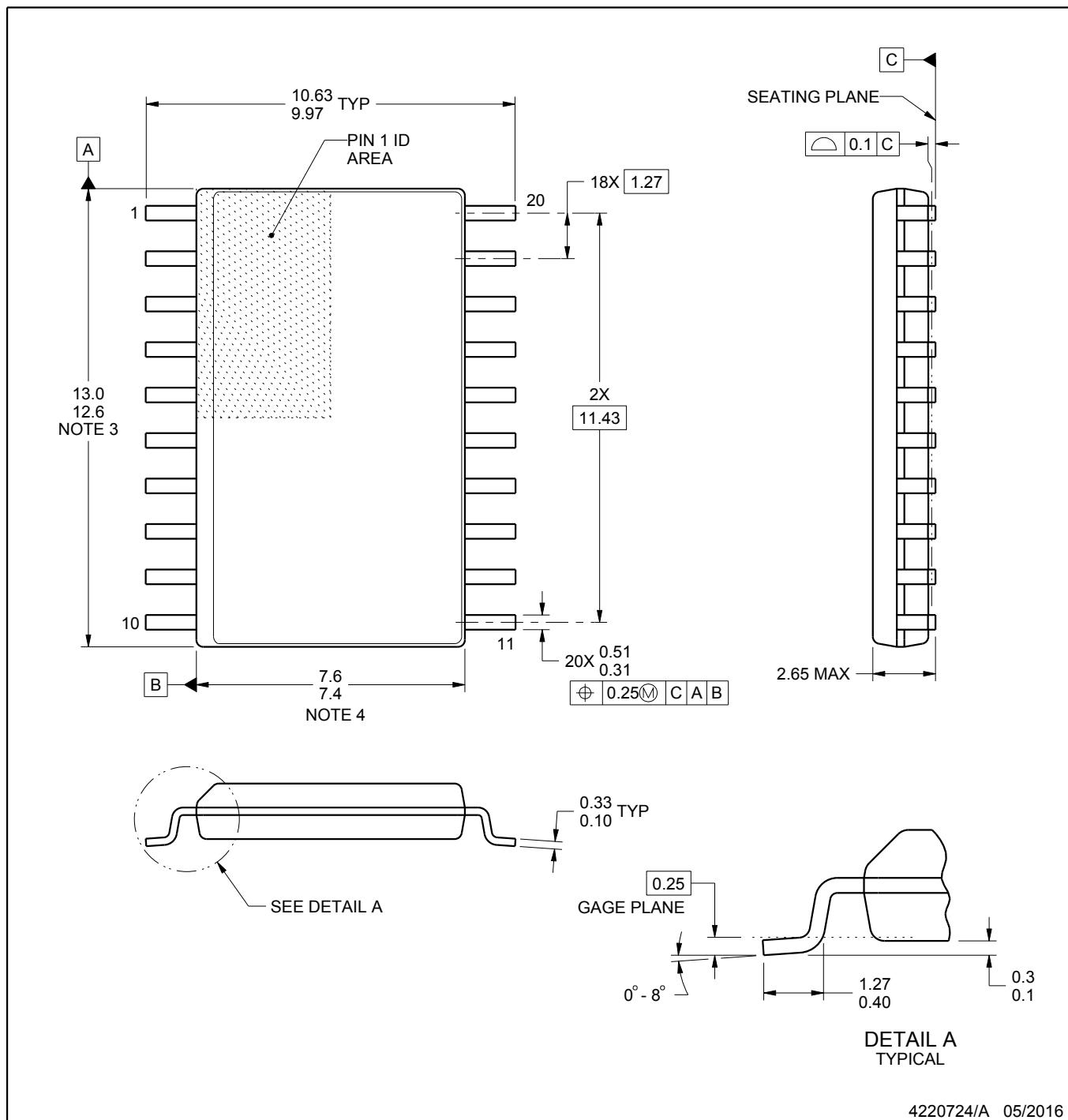


PACKAGE OUTLINE

DW0020A

SOIC - 2.65 mm max height

SOIC



NOTES:

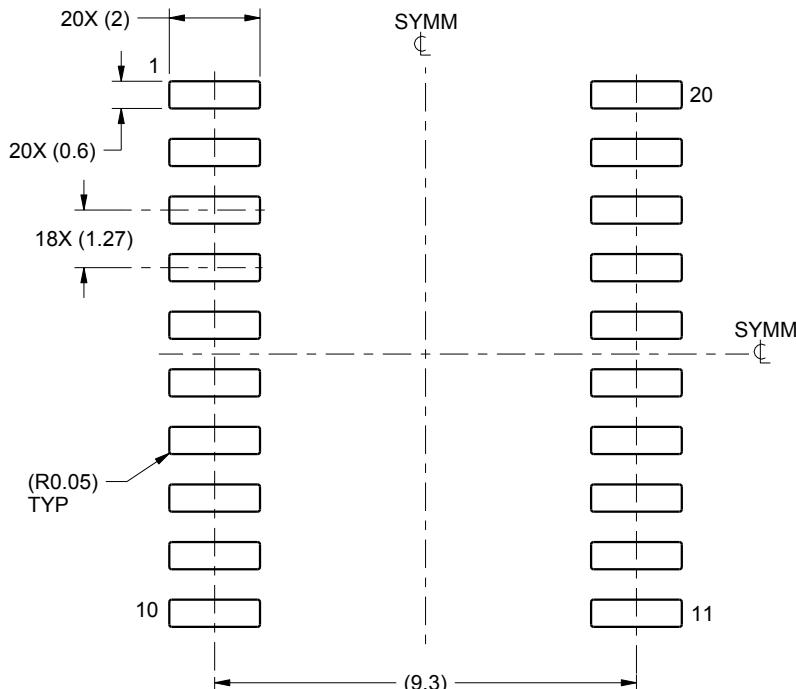
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

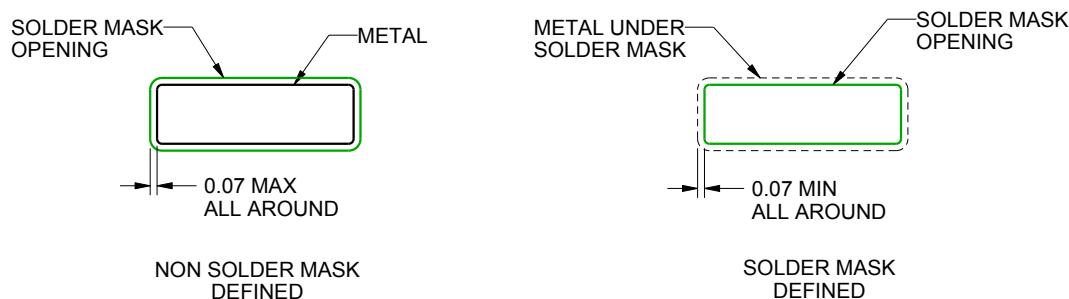
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

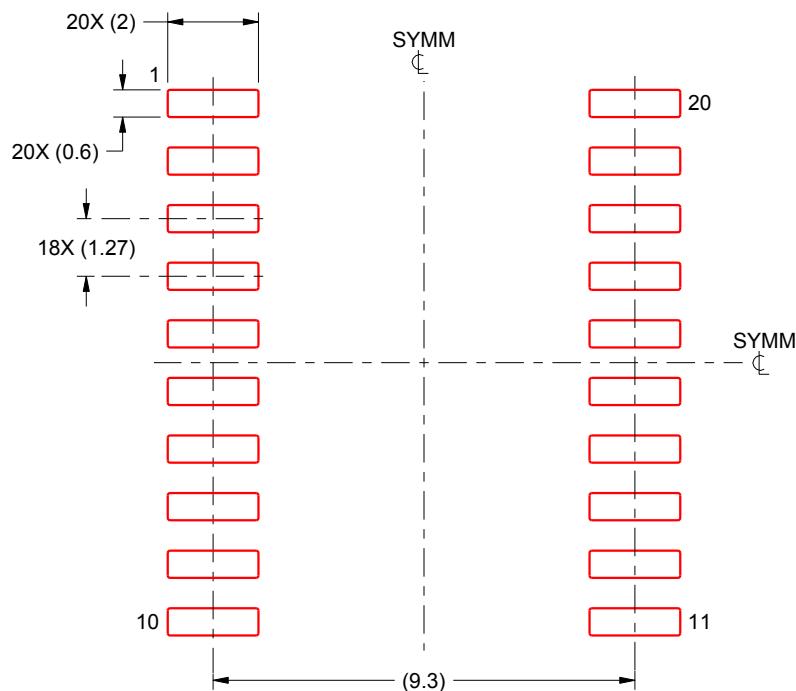
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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